

# Material Composition Specification

DO-35 Case

Available with Pb (lead)-free plating\*



Device average mass .....136 mg  
Fluctuation margin ..... +/-10%

Device part	Substance	mass (mg)
active device	doped Si	0.02
leadframe	alloy -Fe -Cu -Ni	66.5 28.9 3.65
*plating	SnPb20 or Sn (100% tin, Pb-free)	3.04 3.04
encapsulation	glass -PbO -SiO <sub>2</sub>	20.5 13.7

\* specify Lead-free when ordering 100% tin (Pb-free) plating option.